

ABSTRACT OF THE DISCLOSURE

A high-frequency ceramic package 10 comprises a ceramic frame plate 12 brazed to a jointed metal plate 11 on the surface thereof, the jointed metal plate 11 including a substantially rectangular shaped first metal plate 17 which has a hollowed portion 19 at a central portion thereof and a second metal plate 18 which is fitted in the hollowed portion 19 in a state in which the first and second metal plate 17, 18 are jointed together in end-to-end relationship. The first metal 17 is close to the ceramic frame plate in thermal expansion coefficient, and the second metal plate 18 is made from a material having a high level of heat-sinking characteristics. A concave cavity 16 defined between the second metal plate 18 and the ceramic frame plate 12 has a semiconductor electronic component mounting portion on a bottom 16a of the cavity 16.